

L9925

DMOS DUAL FULL BRIDGE DRIVER

- 2 INDEPENDENTLY CONTROLLED H-BRIDGES
- RDS,ON <0.9Ω @ Tamb = 25°C, VS = 14V</p>
- 0.8A DC CURRENT WITHOUT HEAT SINK
- LOW QUIESCENT MODE Iq <200µA
- THEMAL PROTECTION
- CROSS CONDUCTION PROTECTION
- SUPPLY VOLTAGE UP TO 40V
- CMOS COMPATIBLE INPUTS
- OUTPUT SHORT-CIRCUIT PROTECTION

DESCRIPTION

The L9925 is a dual full bridge driver for stepper motor applications. Realized in BCD (Bipolar, CMOS & DOS) techology, logic circuits, precise linear blocks and power transistors are combined to optimize circuit performance and minimize off chip components. Schmitt triggers are used for all input stages and are fully compatible with 5V CMOS logic levels. When both enable signals are low, the IC is commanded to a low quiescent current state and will draw less than 200µA from the battery.

BLOCK DIAGRAM



The charge purp is integrated on chip; no external comporting are required. Full performance is maintaned for 9V <Vs <16V. Extended ranges of 6V <<'s <9V and 16V <Vs <40V yields full functionain but with relaxed performance. Over temcerature protection and ESD protection to all pins ensures relability and reduces system integration failures.



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ABSOLUTE MAXIMUM RATINGS

Absolute Maximum Ratings are those values beyond whih damage to the device may occur. Functional operation under these condition isn't implied.

For voltages and currents applied externally to the device:

Symbol	Parameter	Value	Unit
Vvsdc	Dc Supply Voltage	-0.3 to 26	V
VVSP	Supply Voltage Pulse (T \leq 400ms) ⁽¹⁾	40	V
Ιουτ	DC Output Load Current	±1.2	А
IOUT MAX	DC Output Current: for VOUT > VVS +0.3V or VOUT < -0.3V the internal DMOS reverse and/or substrate diode become conductive and the applied current should not exceed the specified limit.	±1.8	A
VIN1,2	DC Input Voltage	-0.3 to 7	v
VEN	Enable Input Voltage	-0.? w /	V
Tstg, Tj	Storage and Junction Temperature	- 40 .o 150	°C
Ptot	Total Power Dissipation ($T_{pins} = 80^{\circ}C$) ($T_{amb} = 70^{\circ}C$ no copper area on PCB) ($T_{amb} = 70^{\circ}C 8cm^{2}$ copper area on PCB,	5 1.23 2	W W W

(1) Device may be overstressed if pulsed simultaneous with short circuit at one or nore or ne outputs will be present.

PIN CONNECTION



THERMAL DATA

Symbol	Parameter	Value	Unit
TjTS	Thermal Shut-down junction temperature min.	150	°C
Тјтѕн	Thermal Shut-down thereshold hysteresis typ.	25	°C
Rth j-amb	Thermal Resistance Junction-ambient ⁽²⁾	50	°C/W
Rth j-pins	Thermal Resistance Junction-pins	15	°C/W

(2) With 6cm² on board heat sink area

PIN FUNCTIONS

Ν.	Name	Function
1	PGND1	Ground for DMOS sources in bridge 1
2	IN1	Digital Input from motor controller for bridge 1
3	EN1	Logic enable/disable for bridge 1 (active high)
4, 5	NC	No connect
6	OUT1	Output of one half of bridge 1
7, 8	GND	Ground
9	OUT3	Output of one half of bridge 2
10, 11	NC	No connect
12	EN2	Logic enable/disable for bridge 2 (active high)
13	IN3	Digital Input from motor controller for bridge 2
14	PGND2	Ground for DMOS sources in bridge 2
15	NC	No connect
16	IN4	Digital Input from motor controller for bridge 2
17	OUT4	Output of one half of bridge 2
18, 19	NC	No connect
20	VS2	Supply Voltage for bridge 2
21, 22	GND	Ground
23	VS1	Supply Voltage for bridge 1
24, 25	NC	No connect
26	OUT2	Output of one half or bridge 1
27	IN2	Digital Input from motor controller for bridge 1
28	NC	No conne-t

ELECTRICAL CHAP.A (i) FISTICS (Vs = 9 to 16V; T_j = -40 to 150°C ⁽³⁾, unless otherwise specified.)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
ls	Ouioscent Current	EN1 = EN2 =0V; Tj = 85°C			200	μA
		EN1 = EN2 =5V; I _{load} = 0A		5	12	mA
P.1s	Switch on Resistance	$T_j = 25^{\circ}C; V_S = 14V; I_o = 300mA$		0.75	0.8	Ω
N°		$T_j = 125^{\circ}C; V_S = 6V; I_0 = 300mA$		1.5	1.9	Ω
Td-on	Turn-on delay	See Fig 1		10	50	μs
Td-SB	Standby setting time	See Fig 1		50	200	μs
T _{d-off}	Turn-off delay	See Fig 1		10	50	μs
trise	Output rise time (10 to 90%)	See Fig 1	0.5	5	20	μs
tfall	Output fall time (90 to 10%)	See Fig 1	0.5	5	20	μs
ILo	Output leakage current	$EN = 0V$; $V_0 = Vs$ or GND	-10		10	mA
INx, ENx	Logic Input Low voltage		-0.3		1.5	V
	Logic Input High voltage		3.5		6	V
	Hysteresis		0.5	1.0	2.0	V
Ibias	Input bias current		-50		300	μA

The voltage refered to GND and currents are assumed positive, when the current flows into the pin. (3) Tested up to 125°C, parameter guaranted by correlation up to 150°C

Logic Levels

All inputs are positive, non inverting logic

Logic State	Voltage Range
0	-0.3 to 1.5V
1	3.5 to 6.0V

Truth Table

Enable/ Disable

EN1	EN0	Bridge 1	Bridge 2	lq
0	0	Disabled	Disabled	<200µA
0	1	Disabled	Enabled	<12mA
1	0	Enabled	Disabled	<12mA
1	1	Enabled	Enabled	<12mA

Figure 1. Timing Diagram

General Operation

With the bridge enabled, each input INx, maps directly to the corresponding output OUTx.

The output voltage will be equal to the difference between the supply rail and the product of the load current ad the on resistance of the output switch.Vout = V_{supply} - (RDS,ON · ILOAD).

Sourced load currents are positive.

IN1	OUT1	IN2	OUT2	IN3	OUT3	IN4	OUT4
0	0	0	0	0	0	0	0
1	Vs	1	Vs	1	VS	10	١′S
					<u>, 1</u> C		



Tigure 2. Typical Ron - Characteristics of Source and Sink Stage







Figure 4. Application Diagram



Figure 4 shows a typical aprilication diagram for DC motor driving. To assure the safety of the circuit in the reverse battery condition a reverse protection diode D1 is necessary. The transient protection diode D2 must assure that themaximum supply voltage V3 during the transients at the VBAT line VM. be limited to a value lower than the absolute maximu ratings for VvsP. The capacities CB are used to lower Vs-EMR and its values depend on the driving load.

The resistance feedback loop realized by R_0 limited to the μP power supply line by the diode D_0 allows open load detection. To protect the device at the outputs against EMI or ESD > 2KV external capacitors Cex may be used.

CIRCUIT DESCRIPTION

L9925 is a dual full bridge IC designed to drive DC motors, stepper motors and other inductive loads. Eah bridge has 4 power DMOS transistor with RDSon = 0.75Ω and the relative protection and control circuitry (see fig. 5). The 4 half bridges can be controlled independently by means of the 4 inputs IN1, IN3, IN4 and 2 enable inputs ENABLE1 and ENABLE2.

LOGIC DRIVE (true table for the two full bridges)

INPUT	S		OUTPUT
	IN1 IN3	IN2 IN4	MOSFETS
EN1 = EN2 = H	LLHH	L H L H	Sink 1, Sink2 Sink1, Source2 Source1, Sink2 Source1, Source2
@Tj > 150°C	Х	Х	All transistors turned OFF
EN1 = EN2 = L	Х	Х	All transistors turned OFF

L = Low; H = High; X = Don't care

CROSS CONDUCTION

The device guarantees the absence of cross-conduction by watching internal gate-source voltage of the driving power DMOS.

TRANSISTOR OPERATION

ON STATE

When one of POWER DMOS transistors is ON it can be considered as a resistor $R_{DS(ON)} = 0.75\Omega$ at a junction temperature of 25°C

In this condition the dissipated power is ginen by:

$$PON = RDS(ON) \cdot IDS^2$$

The low RDS(ON) of the Multipower BCD process can provide high currents with low power dissipation.

OFF STATE

When one of the POWER DMOS transistor is OFF the VDs voltage is equal to the supply voltage and only the leakage current loss flows.

The power dissipation during this period is given by:

$$POFF = Vs \cdot Idss$$

TRANSITIONS

Like all MOS power transistors the DMOS POWER transistors have an intrinsic diode between their source and drain that can operate as a fast freewheeling diode in switched mode applications. During recirculation with the ENABLE input is low, the POWER MOS is OFF and the diode voltage it is clamped to its characteristics. When the ENABLE input is low, the POWER MOS is OFF and the diode carries all of the recirculation current. The power dissipated in the transitional times in the cycle depends upon the voltage and current waveforms in the application.

 $P_{trans} = I_{DS}(t) \cdot V_{DS}(t)$



Figure 5b. One phase chopping



Figure 5c. Enable chopping



6/9

THERMAL PROTECTION

A thermalprotection circuit has been included that will disable the device if the junction temperature reaches 150°C. When the temperature has fallen to a safe level the device restarts under the control of the input and enable signals.

APPLICATION INFORMATION

RECIRCULATION

During recirculationwith the ENALBE input high, the voltage drop across the transistor is RDs(ON). for voltages less than 0.6V and is clamped at a voltages depending on the characteristics of the source-drain diode for greater voltages. Although the device is protected against cross conduction.

POWER DISSIPATION each bridge

In order to achieve the high performance provided by the L9925 some attention must be paid t ensure that it has an adequate PCB area to dissipate the heat. The forst stage of any thermal design is to calculate the dissipated power in the application, for this example the half step operation shown in Fig. 6 is considered.

RISE TIME TR

When an arm of the half bridge is turned or, current begins to flow in the inductive locd or til the maximum current I_{L} is reached after a time TR, The dissipated energy EOFF/ON.

$$\mathsf{EOFF/ON} = [\mathsf{PD^{c}}(\mathsf{CN}) \cdot \mathsf{IL}^2 \cdot \mathsf{TR}] \cdot \frac{2}{2}$$

Figure 6.



ON TIME TON

During this time the energy dissipated is due to the ON resistance of the transistors $\ensuremath{\mathsf{E}}\xspace{\mathsf{N}}\xspace{\mathsf{N}}$ and the

commutation ECOM. As two of the POWER DMOS transistors are ON EON is given by:

 $\mathsf{EON} = \mathsf{IL}^2 \cdot \mathsf{RDS}(\mathsf{ON}) \cdot 2 \cdot \mathsf{TON}$

In the commutation the energy dissipated is:

 $Econ = Vs \cdot IL \cdot Tcom \cdot fswitch \cdot Ton$

Where:

 $\mathsf{TCOM} = \mathsf{Communication} \ \mathsf{Time} \ \mathsf{and} \ \mathsf{it} \ \mathsf{is} \ \mathsf{assumed} \ \mathsf{that};;$

 $T_{COM} = t_{rise} = t_{fall} \le 20 \mu s$

TSWITCH = Chopper frequency

FALL TIME TF

For this example it is essumed that the energy dissipated in this part of the cycle takes the same form as that shown for the rise time:

$$F_{OFF/ON} = [RDS(ON) \cdot IL^2 \cdot TF] \cdot \frac{2}{3}$$

CUIESCENT ENERGY

The last contribution of the energy dissipation is due to the quiescrent supply current and is given by:

 $\mathsf{EQUIESCENT} = \mathsf{I}\mathsf{QUIESCENT} \cdot \mathsf{VS} \cdot \mathsf{T}$

TOTAL ENERGY PER CYCLE

 $ETOT = (2 \cdot EOFF/ON + EON + ECOM) bridge1+ + (2 \cdot EOFF/ON + EON + ECOM) bridg2 + EQUIESCENT$

The total power dissipation PDIs is simply:

$$P_{DIS} = \frac{E_{tot}}{T}$$

 T_R = Rise time T_{ON} = ON time T_F = Fall time T_{OFF} = OFF time T = Period

$$T = TR + TON + TF + TOFF$$

DIM.		mm			inch	
Dini.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А			2.65			0.104
a1	0.1		0.3	0.004		0.012
b	0.35		0.49	0.014		0.019
b1	0.23		0.32	0.009		0.013
С		0.5			0.020	
c1			45° ((typ.)		
D	17.7		18.1	0.697		0.713
E	10		10.65	0.394		0.419
е		1.27			0.050	
e3		16.51			0.65	
F	7.4		7.6	0.291		0.299
L	0.4		1.27	0.016		0.050
S			8 ° (n	nax.)		



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